

Thermal Pad

Our Thermal Foams also called Gap Pad or Gap Filler are silicone-based thermo-conductive materials that solve the problems of heat dissipation. TGF_045_U is a mattress specially developed for applications where a low cooling requirement is required. Indeed, it is a GOOD thermal conductor of 4.5W/ mK, with a good thermal resistance thus facilitating the transfer of heat and also has an excellent electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

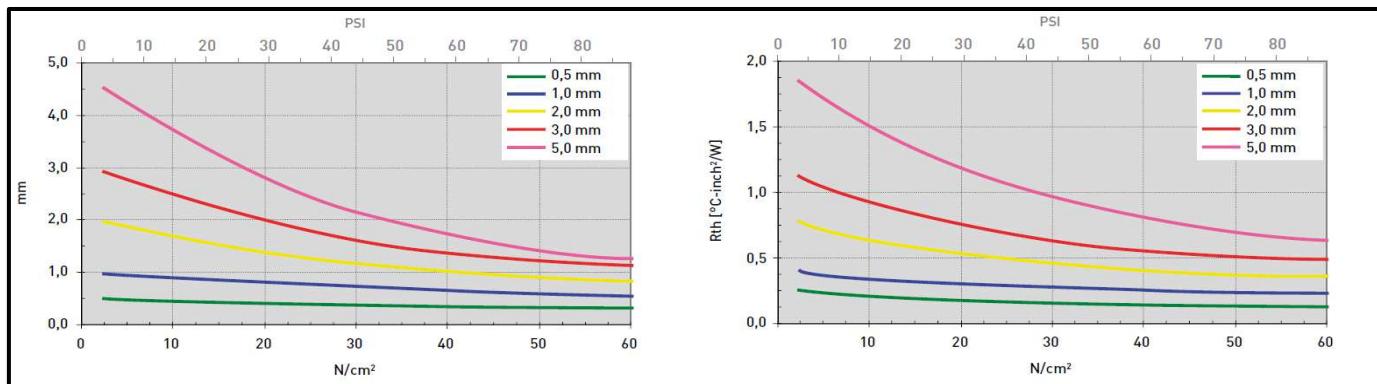


Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, etc.

Technical characteristics

Features	Unit	TGF_045_U			
Thickness	mm	0.5	1	2	3
Reinforcement	-		-		
Color	-		Gray		
Hardness	Shore 00		60		
Size	mm		300*400		
Resistance @60 Psi	°C-inch ² /W (mm)	0.15 (0.35)	0.27 (0.65)	0.42 (1.03)	0.57 (1.40)
Resistance @30 Psi		0.17 (0.40)	0.32 (0.81)	0.55 (1.40)	0.78 (1.98)
Resistance @10 Psi		0.22 (0.45)	0.36 (0.91)	0.68 (1.77)	0.99 (2.63)
Thermal conductivity	W/mK		4.5		
Temperature	°C		-60 to 180		
Breakdown voltage	kV/mm		15		
Volume resistance	0hm - cm		-		
Contante dielectric	@1MHz		-		

The TGF_045_U is available in 0.5/1/1.5/2/2.5/3/4/5mm thicknesses.



Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.